12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20210915000.1
Qualify additional Assembly sites for select SOT devices
Change Notification / Sample Request

Date: September 20, 2021
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210915000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA195AIDBVT	null
LM2731YMF/NOPB	null
LM2831XMF/NOPB	null
LM3671MF-3.3/NOPB	null
LM7301IM5/NOPB	null
LM8261M5/NOPB	null
LMC7111BIM5X/NOPB	null
LMH6624MF/NOPB	null
LMH6642MF/NOPB	null
LMP7701MF/NOPB	null
LMR62014XMF/NOPB	null
LMV321IDBVR	null
LMV331IDBVR	null
LMV651MF/NOPB	null
LP2981AIM5-3.3/NOPB	null
LP2981IM5-3.3/NOPB	null
LP2985A-33DBVTE4	null
LP2985AIM5-3.3/NOPB	null
LP2985AIM5-5.0/NOPB	null
LP2985IM5-3.0/NOPB	null
LP2992AIM5-3.3/NOPB	null
LP5907MFX-3.3/NOPB	null
OPA188AIDBVT	null
OPA244NA/250	null
OPA317IDBVT	null
OPA320AIDBVT	null
OPA365AIDBVR	null
OPA378AIDBVT	null
SN6501DBVT	null
SN65LVDS2DBVT	null
SN74AHCT1G125DBVR	null
SN74LVC1G07DBVR	null
SN74LVC1G14DBVR	null
SN74LVC1G32DBVR	null
TL331IDBVR	null
TL431IDBVR	null
TLV271IDBVR	null
TPS2051BDBVT	null
TPS3825-33DBVT	null
TPS60400DBVT	null
TPS60403DBVT	null
TPS61041DBVR	null
TPS61097-33DBVT	null
TPS62203DBVT	null
TPS76301DBVR	null
TPS76301DBVT	null
TPS76333DBVT	null
TPS79328DBVRG4	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210915000.1	**PCN Date:**	September 20, 2021
Title:	Qualify additional Assembly sites for select SOT devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Dec 20, 2021	**Estimated Sample Availability:**	Provided upon Request
Change Type:			

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:

SOT-23 (DBV)	
Assembly Sites	TIPI, ASEWH, HFTF, HNA, TFME, TIEM, CDAT
Lead Finish	NiPdAu; NiPdAuAg; Matte Sn
Mount compound	400180 A-03 4213245 400194 4207123
Mold Compound	R-27 8097131 R-13 450413 R-04 450042 4222198

Upon expiration of this PCN, TI will combine lead free solutions in a single ***standard part number***, for example; ***INA193AIDBVR***– can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. ***INA193AIDBVRG4.***″

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

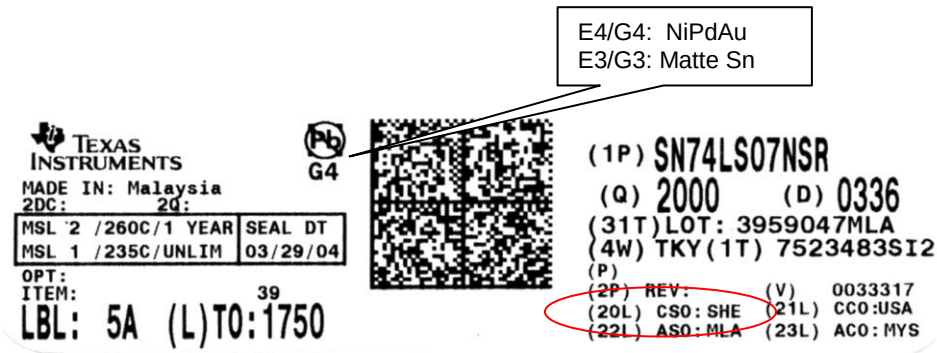
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site		
TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI
ASEWH	Assembly Site Origin (22L)	ASO: AWH
HFTF	Assembly Site Origin (22L)	ASO: HFT
HNA	Assembly Site Origin (22L)	ASO: HNT
TFME	Assembly Site Origin (22L)	ASO: NFM
TI Chengdu (CDAT)	Assembly Site Origin (22L)	ASO: CDA
TI Melaka (TIEM)	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)



Product Affected:

Refer to page 2 of this document to view your affected products

DBV (SOT-23) Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/- (Note a)
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74AHC1G14DBV	HNA INA293A1IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (SN74LVC1GU04DBV)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TIEMA DAC121S101CIMK	HFTAT TLV70333DBV	ASEWH TL431CDBV
TC	Temperature Cycling -65/150C	500 Cycles	-	3/231/0	3/231/0
TC	Temperature Cycling -55/150C	1000 Cycles	3/231/0	-	-
HAST	Biased HAST 130C/85%RH	96 hours	-	3/231/0	3/231/0
THB	Temperature Humidity Bias 85C/85%RH	1000 hours	3/231/0	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM2660MM/NOPB)	3/66/0 (TLV74333PDBV)	3/66/0
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.
Note a – Data collection in progress. Data will be made available upon request after completion.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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